# MTM23223

### Silicon N-channel MOSFET

For switching circuits

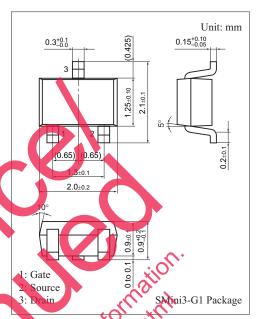
#### ■ Features

- Low voltage drive (2.5 V, 4 V)
- Realization of low on-resistance, using extremely fine process

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Drain-source surrender voltage	V <sub>DSS</sub>	20	V	
Gate-source surrender voltage	V <sub>GSS</sub>	±10	V	
Drain current	$I_D$	4.5	A	
Peak drain current *1	$I_{DP}$	18	A	
Power dissipation *2	$P_{\mathrm{D}}$	500	mW	
Channel temperature	T <sub>ch</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to ±150	°C	

Note) \*1: Pulse width  $\leq 10 \mu s$ , Duty Cycle  $\leq 1\%$ 



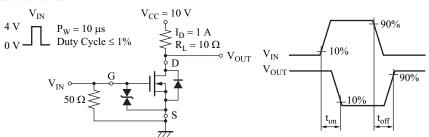
Marking Symbol. BK

### ■ Electrical Characteristics $T_a = 25$ C±3°

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	$V_{ m DSS}$	$I_D = 1 \text{ mA} V_{GS} = 0$	20			V
Drain-source cutoff current	$I_{ m DSS}$	$V_{\rm DS} = 20  \text{V}, V_{\rm OS} = 0$			1.0	μΑ
Gate-source cutoff current	$I_{GSS}$	$V_{GS} = \pm 8$ V, $V_{DS} = 0$			±10	μΑ
Gate threshold voltage	$V_{TH}$	$I_0 = 1.0 \text{ mA}, V_{DS} = 10.0 \text{ V}$	0.4	0.85	1.3	V
Drain-source ON resistance *1 R <sub>D</sub>	D	$V_0 = 1.0 \text{ A}, V_0 = 4.0 \text{ V}$		20	28	
	R <sub>DS(on)</sub>	$I_{\rm D} = 0.6  \text{A}  \text{V}_{\rm GS} = 2.5  \text{V}$		26	40	mΩ
Forward transfer admittance *1	Y <sub>fs</sub>	$I_D \neq OA$ , $V_D \Rightarrow 10 \text{ V, f} = 1 \text{ kHz}$	3.5			S
Short-circuit forward transfer capacitance (Common source)	C <sub>iss</sub>	sit and		1200		pF
Short-circuit output capacitance (Common source)	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$			85		pF
Reverse transfer capacitance (Common source)	$C_{rss}$			80		pF
Turn-on time *2	t <sub>on</sub>	$V_{DD} = 10 \text{ V}, V_{GS} = 0 \text{ V to 4 V}, I_D = 1 \text{ A}$		16		ns
Turn-off time *2	$t_{\rm off}$	$V_{DD} = 10 \text{ V}, V_{GS} = 4 \text{ V to } 0 \text{ V}, I_D = 1 \text{ A}$		220		ns

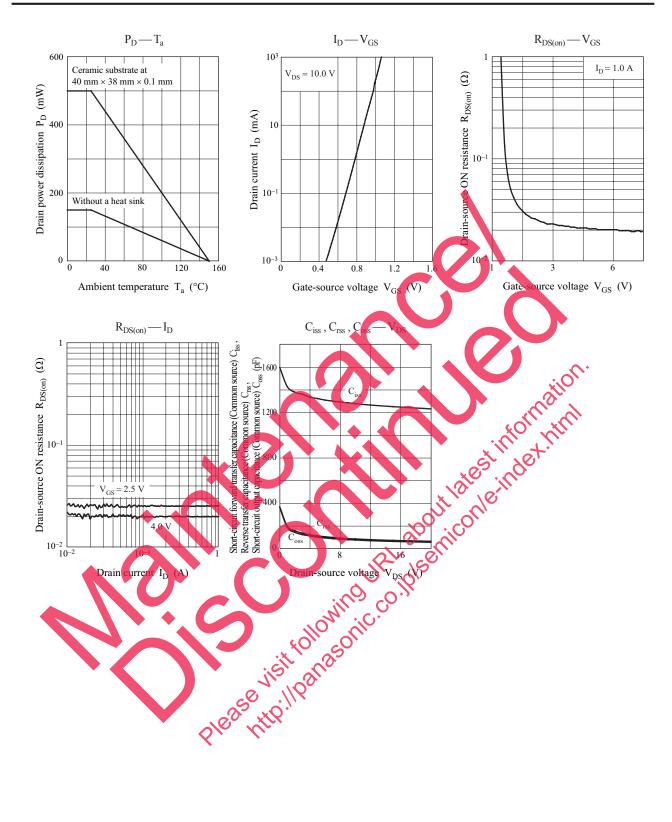
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

- 2. \*1: Pulse measurement: Pulse width < 300 μs, Duty Cycle < 2%
  - \*2:  $t_{on}$  ,  $t_{off}$  measurement circuit



<sup>\*2:</sup> Measuring on ceramic substrate at 40 mm × 38 mm × 0.1 mm Absolute maximum rating without heat sink for P<sub>D</sub> is 150 mW

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